

4/11/2815
PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Mostafazadeh et al.

Attorney Docket No.:
NSC1P217D2/NS-3877-2

Application No.: 09/625,071

Examiner: Clark, S.

Filed: July 25, 2000

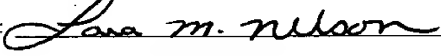
Group: 2815

Title: LEAD FRAME CHIP SCALE PACKAGE

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Commissioner for Patents, Washington, DC 20231 on October 16, 2002.

Signed: 
Lara M. Nelson

AMENDMENT TRANSMITTAL

Commissioner for Patents
Washington, DC 20231

Sir:

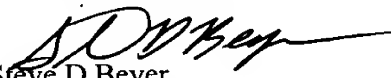
Transmitted herewith is an Amendment in the above-identified application.

The fee has been calculated as shown below.

	Claims After Amendment		Highest Previously Paid For	Present Extra	Small Entity Rate Fee	Large Entity Rate Fee
Total Claims	31	MINUS	34	00	x 9 =	x 18 =
Independent Claims	08	MINUS	08	00	x 42 =	x 84 =
Multiple Dependent Claim Present and Fee Not Previously Paid					\$140.00	\$280.00
Total					\$	\$

- ☐ Applicant(s) hereby petition for a _____ month extension(s) of time to respond to the aforementioned Office Action.
- ☒ Applicant(s) believe that no (additional) Extension of Time is required; however, if it is determined that such an extension is required, Applicant(s) hereby petition that such an extension be granted and authorize the Commissioner to charge the required fees for an Extension of Time under 37 CFR 1.136 to Deposit Account No. 500388.
- ☐ Enclosed is our Check No. _____ in the amount of \$_____ to cover the additional claim fee and/or extension of time fees.
- ☒ Please charge the required fees, or any additional fees required to facilitate filing the enclosed response, to Deposit Account No. 500388 (Order No. NSC1P217D2).

Respectfully submitted,
BEYER WEAVER & THOMAS, LLP


Steve D Beyer
Reg. No. 31,234

P.O. Box 778
Berkeley, CA 94704-0778



* 20/Response
PATENT 10/24/02
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Signed: Lara M. Nelson
Lara M. Nelson

AMENDMENT B

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the final Office Action dated July 25, 2002, the period for response to which extends through October 25th, 2002, please enter the following remarks

REMARKS

The outstanding rejections of the claims are respectfully traversed for the following reasons.

Claim 11-12 – Figures 1(a), 1(b) and 1(c) are NOT admitted to be Prior Art

In the outstanding Office Action Claims 11 and 12 were rejected under 35 U.S.C. § 103 as being unpatentable over Figures 1a- 1d of the present application. These rejections are respectfully traversed. The inventors believe that the lead frame illustrated in Fig. 1(a) and 1(b), as well as the package illustrated in Fig. 1(c) is part of their invention. It is acknowledged that the packages illustrated in Figs 1(d) are prior art.